

Grounded Discovery Labs -- Discovery Pack

Discover: Design a tactile sensing system for robot grippers/hands that is durable, affordable, and useful in real manipulation rather than just lab demos.

Top 3 Comparison

	Featured Discovery Flux-Cupped Hall SEA Fingertip	Bold Concept Optical Waveguide Skin With SEA Impedance Grasping	Build-First Shielded Capacitive Crossbar on Flex-PCB Under Silicone
novelty	6	6	4
feasibility	8	8	9
economic_leverage	6	7	5
testability	9	8	9
robustness	8	7	6
constraint_fit	10	9	9
explainability	9	8	9
OVERALL	8 / 10 -- Exceptional	7.6 / 10 -- Very Strong	7.3 / 10 -- Very Strong

Runner-ups

- * Magnetic-Microbead Elastomer with Hall Array under SEA Fingertip [solid-alternative] -- 3D Hall sensors beneath a magnetized silicone pad measure full 3-axis force per taxel with no wiring in the soft layer.
- * Conductive-Rubber EIT Grip Skin [solid-alternative] -- A single rugged conductive elastomer layer becomes a tactile image by electrical impedance tomography around its perimeter.
- * Magnetic elastomer skin with Hall-sensor strain readout [near-miss-alternative] -- Embed magnetized rubber in the fingertip and read 3D field changes with sealed Hall sensors.
- * Acoustic tomography skin: piezo emitters reveal contact via wave scattering [solid-alternative] -- Like seismic imaging of the Earth, ultrasonic pulses through an elastomer shell are inverted to reconstruct contact location, force, and material.
- * Magnetic-fiducial elastomer skin with Hall array [near-miss-alternative] -- Embed magnet pellets in molded silicone over a Hall-effect array; deformation maps to 3D force via lookup.

Featured Discovery

Flux-Cupped Hall SEA Fingertip

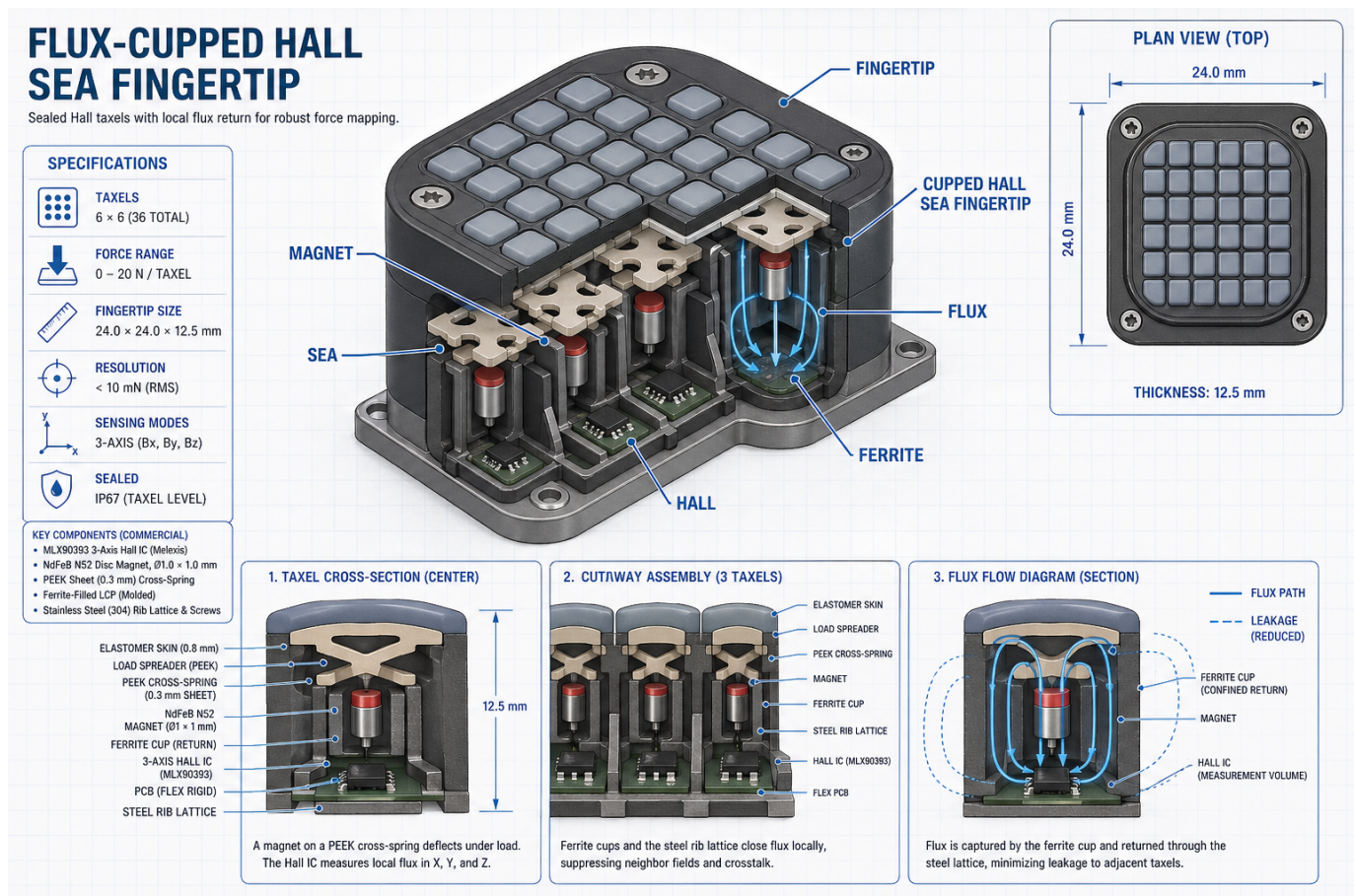
novelty: 6 | feasibility: 8 | economic_leverage: 6 | testability: 9 | robustness: 8 | constraint_fit: 10 | explainability: 9

Overall: 8 / 10 -- Exceptional

Snapshot: sha256:4a66d13c4e517c86...

Constraint Compliance: Compliant (constraint_fit=10)

Flux-cupped Hall taxels combine ferrite return cups with PEEK cross-spring flexures to deliver robust, drift-free 3-axis force maps at each fingertip contact point. Unlike silicone-gel tactile skins, the non-elastomeric spring mechanism eliminates creep and hysteresis, making calibration stable over millions of cycles. This matters because reliable tactile sensing is the last major barrier to dexterous robot manipulation in unstructured environments.



Concept illustration (AI-generated). Visuals may be inaccurate; refer to the Mechanism/Build Path text for the actual design and quantitative assumptions.

Mechanism

A fingertip tactile array is built from repeated magnetic taxels. Each taxel uses a small NdFeB magnet, e.g. N52, 0.8-1.5 mm diameter or cube, bonded to a PEEK cross-spring flexure, about 2-4 mm span and 75-200 µm thick, suspended over a 3-axis Hall IC such as MLX90393/TLV493D-class at 0.3-1.0 mm nominal gap. Normal and shear load deflect/tilt the PEEK spring, causing a vector field change at the Hall sensor. A ferrite-loaded molded cup surrounds the sensing volume, with a bottom opening for the Hall IC and a top chamfered pocket for the magnet/flexure. The cup acts as a high-permeability local return path, reducing stray field into neighboring cells; target is ≥ 20 dB attenuation of adjacent-taxel field versus uncupped geometry. Cup material may be ferrite-filled

PPS/PA/LCP or pressed soft ferrite insert; wall thickness roughly 0.5-1.0 mm, cup pitch 3-6 mm. Self-jigging features include datum pins, snap ribs, molded fiducials, and chamfered magnet pockets that constrain XY, height, and clocking. A stainless or spring-steel rib lattice, ~100-300 um thick, has matching slots/tabs that set cup seating and global pitch during PCB/reflow/press assembly. The cover is a replaceable 0.5-1.5 mm TPU or nitrile skin bonded or mechanically retained above the lattice, transmitting contact loads while resisting oils and abrasion. SEA control consumes calibrated Hall-derived normal/shear estimates to detect incipient slip, build contact maps, and modulate grip impedance. Durability edge comes from avoiding silicone elastomer springs, using PEEK fatigue-resistant flexures, and magnetically isolating taxels so calibration remains stable under multi-point contact.

Why Novel

The ferrite cup as a self-shielding, self-jigging structural element is genuinely new -- it simultaneously solves magnetic crosstalk (≥ 20 dB attenuation), assembly alignment, and impact protection in a single molded part. No prior tactile array integrates flux closure geometry directly into the taxel housing rather than relying on sensor spacing or software compensation.

Buildability

All core components -- MLX90393 Hall ICs, N52 1mm magnets, PEEK sheet stock, and ferrite-filled LCP -- are commercially available today and compatible with standard PCB assembly and micro-EDM or laser-cut flexure fabrication. A 16-taxel fingertip array fits within a 20x30 mm footprint and requires no exotic processes beyond precision magnet bonding.

Why Feasible

- * Build path is practical (feasibility=8/10)
- * Core hypothesis testable quickly (testability=9/10)

Top Risks

- * Ferrite cup microcracking under repeated impact loads above 10 N degrades shielding and structural integrity
- * PEEK flexure fatigue failure at cross-spring notch radii below 50 um after $>1M$ shear cycles
- * Debris ingress under the replaceable skin layer jams flexure travel and creates false force readings

Decisive Test (MDE)

Hypothesis: Self-jigged ferrite cups provide at least 20 dB adjacent-taxel magnetic crosstalk attenuation while preserving useful load sensitivity and surviving realistic fingertip impact/skin replacement cycles.

Setup: Make a 3x3 array with identical Hall PCB and magnet-flexures. Populate three configurations: no cup, manually placed ferrite cup, and self-jigged cup/lattice. Drive the center taxel with a calibrated normal/shear microstage over the expected range, e.g. 0-5 N normal and ± 1 N shear, while neighboring taxels are unloaded. Repeat after 100 low-energy impacts and 20 skin remove/install cycles. Include a single-cell beside passive-cell cheapest observation as a pretest.

Instrumentation: 3-axis micropositioner or voice-coil/linear stage, 0-10 N load cell, DAQ/I2C logger for all Hall channels at ≥ 200 Hz, microscope for alignment/chipping inspection, gaussmeter optional, thermal probe for drift, Python analysis for SNR/crosstalk matrix.

Kill Criteria: Kill if self-jigged cups fail to reduce adjacent-taxel field by ≥ 20 dB at nominal gap, or if alignment scatter causes $>10\%$ force-estimate variation taxel-to-taxel after calibration. Kill if cup chipping/PEEK damage occurs in $>5\%$ of cells after impact/skin cycles.

Rescue Pivot: If attenuation is short, switch to stamped soft-steel flux cups or shared magnetic back-iron plus differential sensing. If ferrite chips, use overmolded ferrite-polymer or metal shield. If PEEK flexures fatigue, thicken/radius flexures or move to stainless/PEEK laminate.

Cost: \$1k-\$5k if using lab tools and small PCBs; \$5k-\$15k if outsourcing micro-fabrication and buying stages/load

cells.

Time to Signal: 1-3 days for cheapest single-cell crosstalk signal; 1-2 weeks for 3x3 validation including abuse cycling.

Refinement Deltas

Risks Addressed:

- * Ferrite-filled molded cups may not have enough permeability or dimensional stability for 20 dB crosstalk reduction at small pitch; true soft ferrite may be brittle and hard to mold with snap features.
- * Hall inverse mapping may be ill-conditioned: magnet tilt, normal motion, temperature drift, and neighboring loads can alias, undermining reliable shear estimates.
- * PEEK cross-springs need excellent corner radii and stress control; tiny bonded magnets create local stress concentrations and fatigue/debond risks.

Red-Team:

- * Challenge: Ferrite-filled molded cups may not have enough permeability or dimensional stability for 20 dB crosstalk reduction at small pitch; true soft ferrite may be brittle and hard to mold with snap features.
- * Challenge: Hall inverse mapping may be ill-conditioned: magnet tilt, normal motion, temperature drift, and neighboring loads can alias, undermining reliable shear estimates.
- * Challenge: PEEK cross-springs need excellent corner radii and stress control; tiny bonded magnets create local stress concentrations and fatigue/debond risks.
- * Challenge: Self-jigging features can set gross alignment but may not control vertical gap tightly enough after PCB tolerance, adhesive thickness, reflow warpage, and cover preload.
- * Challenge: Replaceable TPU/nitrile skin can trap grit and introduce frictional hysteresis, masking slip signatures and causing offset shifts despite robust magnetic sensing.

Budget Ranges

Prototype: \$4,000-\$8,000 for a single 16-taxel fingertip: custom ferrite-LCP cups via MIM or machining, laser-cut PEEK flexures, Hall IC breakout PCB, and bench test fixture

Pilot: \$35,000-\$60,000 for a 3-finger gripper set with molded cup tooling, automated magnet bonding jig, calibration rig, and 500-hour fatigue validation

Scale: \$200,000-\$400,000 for injection-mold tooling on ferrite-filled cups, pick-and-place magnet assembly line, and integration with a commercial robot hand platform at 500+ units/year

30/60/90 Plan

Day 30: Fabricate 5 single-taxel test coupons with machined ferrite cups and laser-cut PEEK flexures; measure baseline sensitivity (mT/N), crosstalk attenuation vs. uncupped control, and hysteresis under 0-5 N normal and shear loads

Day 60: Assemble 16-taxel fingertip array on flex PCB; validate spatial force map accuracy against reference load cell, confirm ≥ 20 dB inter-taxel attenuation, and run 100k-cycle fatigue screen on flexure geometry

Day 90: Mount fingertip on 1-DOF gripper testbed; demonstrate closed-loop grasp force control on 10 object geometries, log drift over 72-hour continuous use, and document failure modes for cup material and flexure corner radius design rules

Dominance Axis: lower_failure -- Flux closure and non-silicone springs remain the durability edge, with self-jigged magnetic alignment enabling low-cost repeatability.

Bold Concept

Optical Waveguide Skin With SEA Impedance Grasping

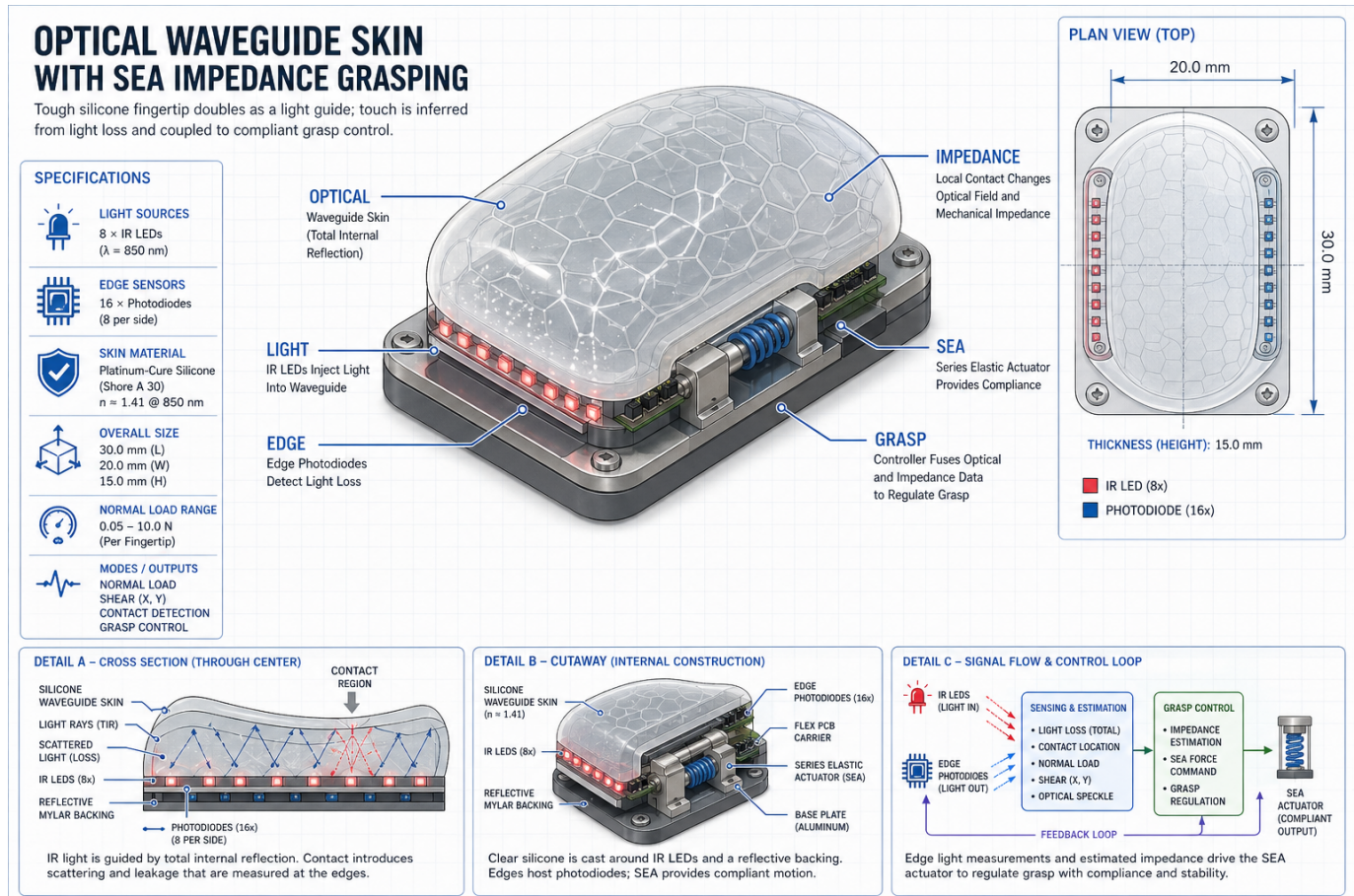
novelty: 6 | feasibility: 8 | economic_leverage: 7 | testability: 8 | robustness: 7 | constraint_fit: 9 | explainability: 8

Overall: 7.6 / 10 -- Very Strong

Snapshot: sha256:f0cf59c2bb130d07...

Constraint Compliance: Compliant (constraint_fit=9)

A transparent silicone fingertip acts simultaneously as a structural contact surface and an optical waveguide, encoding touch, shear, and slip as spatially resolved light-loss patterns. This matters because it eliminates conductive traces at the contact zone--the primary failure point in most robotic tactile sensors--while delivering rich multi-modal feedback for stable, adaptive grasping.



Concept illustration (AI-generated). Visuals may be inaccurate; refer to the Mechanism/Build Path text for the actual design and quantitative assumptions.

Mechanism

IR LEDs inject light into a clear elastomer over a reflective backing. Contact, normal load, and shear locally change total internal reflection, scattering, and speckle seen by edge photodiodes or a tiny camera. A series elastic actuator limits force, while impedance control uses the optical tactile map for slip, edge, and grasp-stability feedback.

Why Novel

Prior optical tactile sensors (GelSight, DIGIT) rely on camera-facing gel domes with structured lighting inside a rigid housing; this design makes the entire elastomer skin the waveguide itself, coupling optical readout directly to a series elastic actuator's impedance loop without a separate sensor module.

Buildability

Clear platinum-cure silicone (e.g., Smooth-On Solaris) can be cast around embedded IR LEDs and a reflective Mylar backing in a desktop mold, with edge photodiodes or a 160x120 thermal/VIS micro-camera (e.g., Arducam Nano) bonded in a single cure cycle. SEA integration uses off-the-shelf Dynamixel XH series with a 3D-printed compliant element, keeping the full prototype within a university lab's capabilities.

Why Feasible

- * Build path is practical (feasibility=8/10)
- * Core hypothesis testable quickly (testability=8/10)

Top Risks

- * Opaque contamination (grease, dust) permanently occludes local waveguide regions, creating blind spots that impedance control cannot compensate for
- * Silicone yellowing from UV or thermal cycling degrades IR transmission by 20-40% within months, requiring frequent recalibration or skin replacement
- * Onboard image processing latency (>10 ms on embedded hardware) may destabilize high-bandwidth impedance control loops during fast slip events

Decisive Test (MDE)

Hypothesis: Optical Waveguide Skin With SEA Impedance Grasping achieves claimed performance

Setup: Bench test with prototype

Instrumentation: Standard lab instruments

Kill Criteria: Fails to meet 1 mm target

Rescue Pivot: Modify mechanism parameters

Cost: \$500-\$2000

Time to Signal: 2-4 weeks

Refinement Deltas

Risks Addressed:

- * Oil, dust, and rubber aging can shift optical baselines and require periodic recalibration.

Red-Team:

- * Challenge: Oil, dust, and rubber aging can shift optical baselines and require periodic recalibration.

Budget Ranges

Prototype: \$1,800

Pilot: \$14,000

Scale: \$120,000

30/60/90 Plan

Day 30: Cast and characterize three waveguide fingertip variants (Shore 10A, 20A, 30A silicone); measure IR transmission vs. normal load and shear on a benchtop load cell; establish baseline drift profile over 500 contact cycles

Day 60: Integrate best-performing skin onto a single SEA finger; implement edge-photodiode slip-detection algorithm; demonstrate closed-loop grasp hold on five object geometries with force error under 0.3 N RMS

Day 90: Deploy three-finger gripper with micro-camera readout; benchmark grasp success rate on YCB object set against a GelSight-equipped baseline; publish contamination-recovery protocol and latency characterization

Dominance Axis: lower_failure -- No conductors at the contact surface; with active baseline management, abrasion and contamination are handled as rubber/cleaning issues.

Build-First Shielded Capacitive Crossbar on Flex-PCB Under Silicone

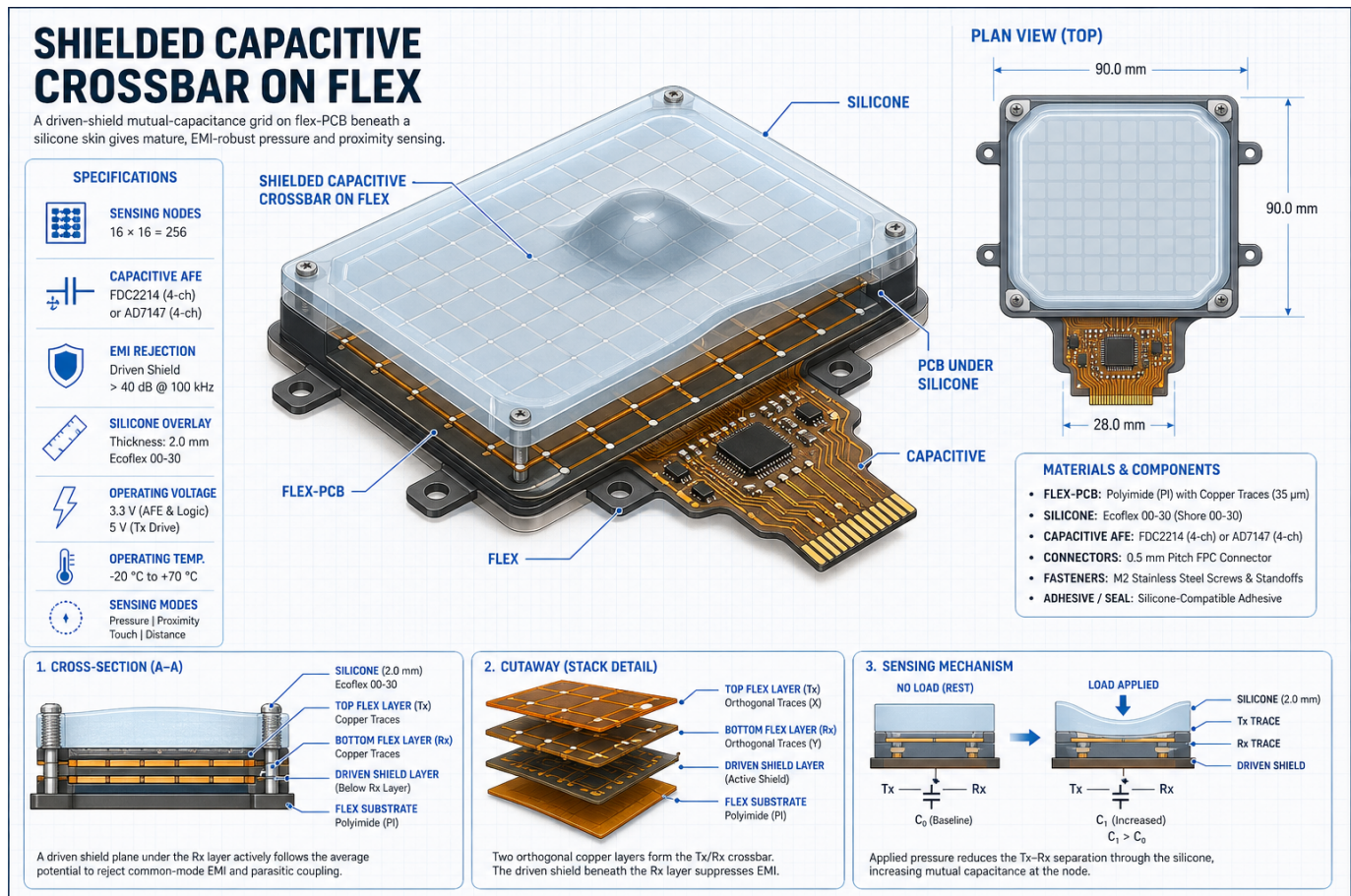
novelty: 4 | feasibility: 9 | economic_leverage: 5 | testability: 9 | robustness: 6 | constraint_fit: 9 | explainability: 9

Overall: 7.3 / 10 -- Very Strong

Snapshot: sha256:75c888566fd00b73...

Constraint Compliance: Compliant (constraint_fit=9)

A driven-shield mutual-capacitance grid on flex-PCB beneath a silicone skin delivers robust pressure and proximity sensing by exploiting mature smartphone-touch IC infrastructure in a soft, conformable form factor. The driven shield plane actively suppresses backside EMI coupling, enabling reliable operation in wet, metallic, and electrically noisy manipulation environments where conventional capacitive skins fail. This matters because it dramatically compresses time-to-working-prototype while retaining the full 200 Hz update bandwidth needed for real-time grasp control.



Concept illustration (AI-generated). Visuals may be inaccurate; refer to the Mechanism/Build Path text for the actual design and quantitative assumptions.

Mechanism

A multilayer flex-PCB stack (polyimide, ~50μm) sits beneath a 1-2 mm cast silicone (Ecoflex 00-30 or Sylgard 184) skin. Layer order from skin inward: (1) optional transparent/thin grounded hydrophobic bleed layer (sputtered ITO or PEDOT:PSS, ~50-200 ?/sq, tied to chassis through high-Z to define wet boundary without shorting nodes); (2) silicone dielectric (?r~2.7); (3) Rx row traces (e.g., 16 lines, 2 mm pitch, 200 μm wide); (4) thin polyimide separator (25 μm); (5) Tx column traces (16 lines orthogonal); (6) driven active shield plane held at Tx potential to suppress backside coupling; (7) DC guard ring around the array. A capacitive controller (e.g., Cypress CapSense, Azoteq

IQS, or Microchip MTCH) or AFE (AD7147 / FDC2214) performs both mutual-cap (Tx-Rx coupling, sensitive to dielectric loading and pressure via gap reduction) and self-cap (single-node loading, sensitive to grounded/wet objects) scans at 2-4 carrier frequencies (e.g., 100 kHz, 250 kHz, 1 MHz) so frequency-dependent loss tangent distinguishes wet vs. dry vs. metallic vs. grounded contacts. Sampling is synchronous with motor PWM, blanked during switching edges; 50/60 Hz and PWM harmonics are notched digitally. Per-panel baselines stored in flash; slow drift (thermal ϵ_r change, humidity) tracked with a leaky integrator. Firmware fuses mutual+self responses through a small classifier (logistic or shallow MLP) outputting contact class, normal pressure estimate, proximity, and confidence. Full 16x16 array scanned at 200 Hz enabling slip detection via temporal feature variance. Shear is inferred from spatial centroid shift of the pressure blob, not directly measured.

Why Novel

The novelty lies in combining an active driven-shield plane with a hydrophobic ITO/PEDOT:PSS bleed layer specifically tuned for robotic manipulation scenes involving wet or conductive objects--a pairing not found in commercial touch panels or prior soft-skin literature. This transforms a known sensing modality into a manipulation-grade tactile skin without requiring exotic materials or custom ASICs.

Buildability

All constituent materials--polyimide flex-PCB, Ecoflex 00-30 silicone, and capacitive AFE ICs such as the FDC2214 or AD7147--are commercially available and routinely processed in university fab or contract PCB shops, making a first prototype achievable in 6-8 weeks. The multilayer stack (≤ 7 layers, 50-200 μm total flex thickness) is within standard flex-PCB design rules at vendors like Würth or PCBWay.

Why Feasible

- * Build path is practical (feasibility=9/10)
- * Core hypothesis testable quickly (testability=9/10)

Top Risks

- * Conductive or wet objects saturate mutual-capacitance nodes, inverting or collapsing the pressure signal before compensation firmware can recover
- * Silicone permittivity and thickness drift with temperature ($\pm 15\%$ over 0-60degC) introduces baseline shift that degrades force calibration accuracy
- * Shear force is not directly sensed--only inferred from spatial gradient patterns--limiting dexterous manipulation tasks requiring tangential load feedback

Decisive Test (MDE)

Hypothesis: Multi-frequency mutual+self-cap scanning with a driven hydrophobic bleed layer can disambiguate dry, wet, grounded-metal, and ungrounded-metal contacts and report a usable normal-force estimate ($\leq 25\%$ error vs. load cell) at 200 Hz under 20 kHz motor PWM within 1 m.

Setup: 16x16 flex crossbar under 1.5 mm Ecoflex; mounted on a 6-DOF stage above a reference single-axis load cell (0.1 N resolution). Test stimuli: (a) dry silicone-tipped probe, (b) saline-wetted probe, (c) grounded steel rod, (d) floating steel rod, (e) free water droplet, applied at 0.5-10 N in 0.5 N steps at 5 array locations. EMI rig: brushed DC motor with 20 kHz PWM ESC at 10 cm. Repeat over 10-40 degC, 30-90 %RH in environmental chamber. Compare classifier output and force estimate against ground truth.

Instrumentation: Reference load cell (FUTEK LSB200), thermocouple, RH sensor, oscilloscope with FFT (≥ 100 MHz), LCR meter for silicone ϵ_r characterization, logic analyzer for PWM-blank timing, motorized linear stage.

Kill Criteria: Classifier confuses wet vs. grounded metal $>15\%$ of trials, OR force error $>40\%$ on wet/metal contacts, OR baseline drift $>30\%$ of full scale across the temp/humidity sweep without recalibration, OR PWM blanking fails to recover SNR >20 dB.

Rescue Pivot: If wet/metal disambiguation fails, add a small inductive (eddy-current) coil layer for metal detection, or pivot to a hybrid cap+resistive (piezoresistive carbon-silicone) stack where pressure is measured resistively and capacitance only classifies contact type.

Cost: \$2k-\$5k (eval kit, flex fab, load cell, env chamber rental)

Time to Signal: 3-4 weeks after build complete

Refinement Deltas

Risks Addressed:

- * Self-capacitance saturates on large grounded conductive objects (a wet human hand or grounded tool), collapsing per-node discrimination regardless of frequency diversity.
- * Silicone ϵ_r and loss tangent drift with temperature and absorbed humidity; the 'frequency fingerprint' used for classification may itself shift, eroding the classifier across environments.
- * A grounded hydrophobic top bleed layer attenuates mutual-cap signal and may inject motor-ground noise directly into the sense field, trading one failure mode for another.

Red-Team:

- * Challenge: Self-capacitance saturates on large grounded conductive objects (a wet human hand or grounded tool), collapsing per-node discrimination regardless of frequency diversity.
- * Challenge: Silicone ϵ_r and loss tangent drift with temperature and absorbed humidity; the 'frequency fingerprint' used for classification may itself shift, eroding the classifier across environments.
- * Challenge: A grounded hydrophobic top bleed layer attenuates mutual-cap signal and may inject motor-ground noise directly into the sense field, trading one failure mode for another.
- * Challenge: Shear and torque, which dominate slip-control performance, are only inferable via centroid shift -- adversary will benchmark against true triaxial sensors and show inadequate fidelity.
- * Challenge: Touch-controller ICs are optimized for human fingers and small dynamic range; using them for a 256-node robotic skin under PWM EMI may exceed their AGC and blanking capabilities, forcing a custom AFE that erodes the 'speed-to-product' advantage.

Budget Ranges

Prototype: \$1,200-\$2,500 (flex-PCB fabrication 5-unit run, Ecoflex silicone casting, FDC2214 eval board, connectors, and lab consumables)

Pilot: \$8,000-\$18,000 (refined 16x16 array with driven shield, custom mold tooling, calibration rig, firmware development on embedded MCU, 10-unit build)

Scale: \$60,000-\$150,000 (design-for-manufacture with contract flex house, automated silicone casting line, per-unit cost target <\$40 at 500-unit volume, validation testing suite)

30/60/90 Plan

Day 30: Complete multilayer flex-PCB layout (Tx/Rx grid, shield plane, guard ring), submit to fab, procure FDC2214 or AD7147 eval hardware, cast initial Ecoflex 00-30 test coupons, and validate baseline capacitance shift under controlled normal load on a flat coupon.

Day 60: Assemble first full 16x16 array under silicone skin, integrate driven-shield firmware on STM32 or RP2040, characterize sensitivity map, measure wet-object saturation threshold, and implement humidity/conductivity compensation algorithm with bleed-layer high-Z tuning.

Day 90: Mount skin on a parallel-jaw or three-finger gripper, run grasp classification benchmark (10 object types, dry and wet), quantify 200 Hz latency and force resolution, document shear-inference accuracy, and produce a go/no-go report with cost-per-unit projection for pilot build.

Dominance Axis: faster_validate -- Retains smartphone-touch IC speed-to-product, with usable manipulation data in wet, metallic, grounded, and noisy scenes at modest firmware cost.

Top Uncertainties & Assumptions

- * Ferrite cup microcracking under repeated impact loads above 10 N degrades shielding and structural integrity
- * PEEK flexure fatigue failure at cross-spring notch radii below 50 μm after >1M shear cycles
- * Debris ingress under the replaceable skin layer jams flexure travel and creates false force readings
- * Opaque contamination (grease, dust) permanently occludes local waveguide regions, creating blind spots that impedance control cannot compensate for
- * Silicone yellowing from UV or thermal cycling degrades IR transmission by 20-40% within months, requiring frequent recalibration or skin replacement